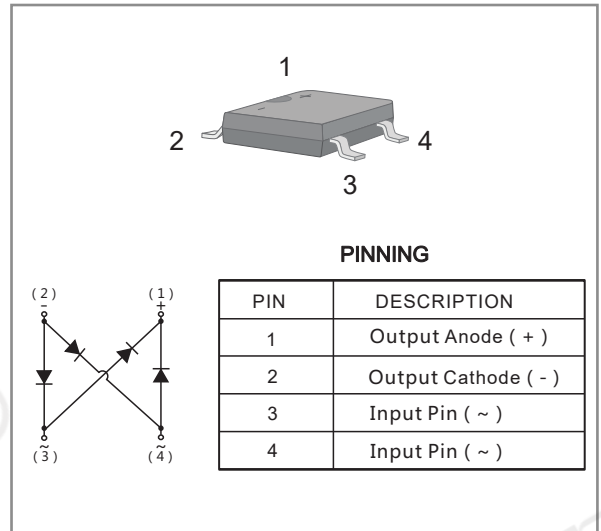


**Features:**

- ☐ Glass Passivated Chip Junction
- ☐ Reverse Voltage - 100 to 1000 V
- ☐ Forward Current - 1.0 A
- ☐ High Surge Current Capability
- ☐ Designed for Surface Mount Application

ABS**Absolute Maximum Ratings** (Ta=25°C unless otherwise noted)

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Parameter	Symbols	ABS201G	ABS202G	ABS204G	ABS206G	ABS208G	ABS210G	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at $T_c = 125^\circ\text{C}$	I_O	1						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Forward Voltage per element @ $I_F = 1.0\text{A}$	V_F	1.1						V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_A = 25^\circ\text{C}$ @ $T_A = 100^\circ\text{C}$ @ $T_A = 125^\circ\text{C}$	I_R	5 50 100						μA
Typical Junction Capacitance (Note1)	C_j	13						pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$ $R_{\theta JC}$	72 20						$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	$-55 \sim +150$						$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with $4 \times 1.5 \times 1.5$ (3.81×3.81 cm) copper pad.



Typical Characteristics

Fig.1 Average Rectified Output Current Derating Curve

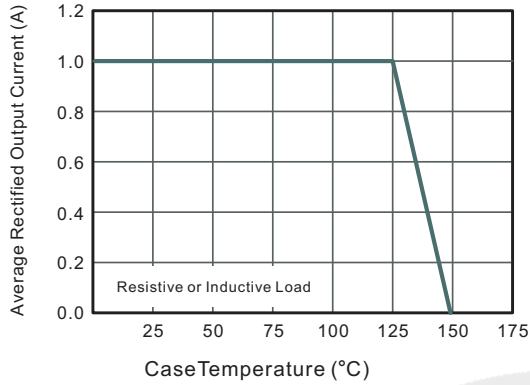


Fig.2 Typical Reverse Characteristics

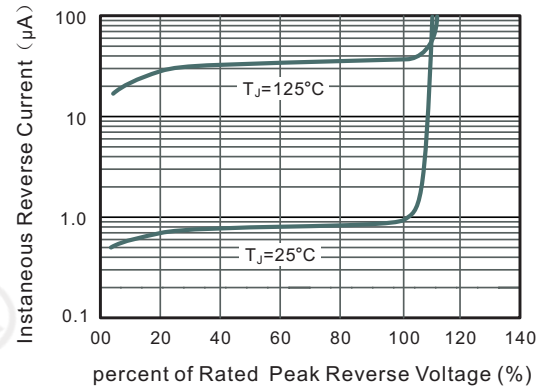


Fig.3 Typical Instantaneous Forward Characteristics

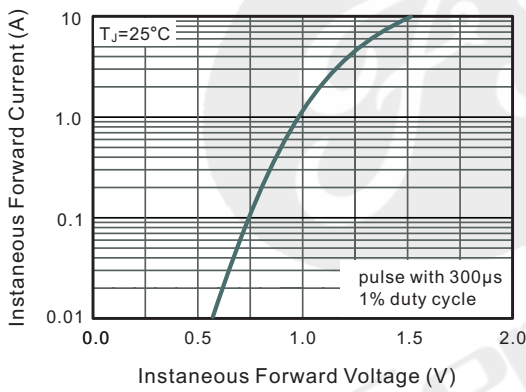


Fig.4 Typical Junction Capacitance

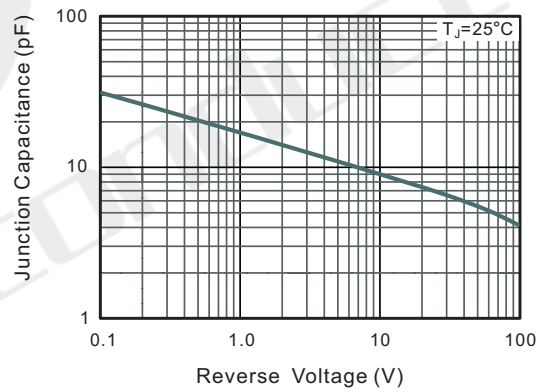
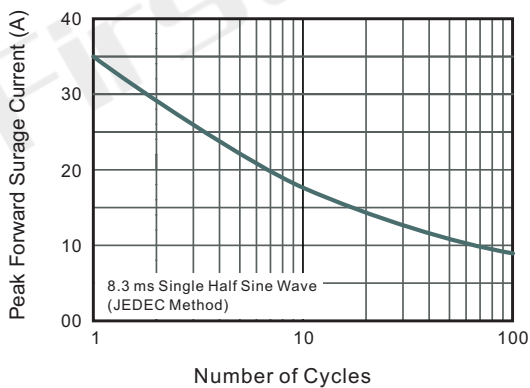


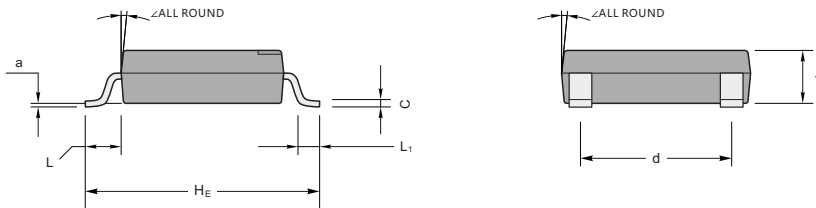
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



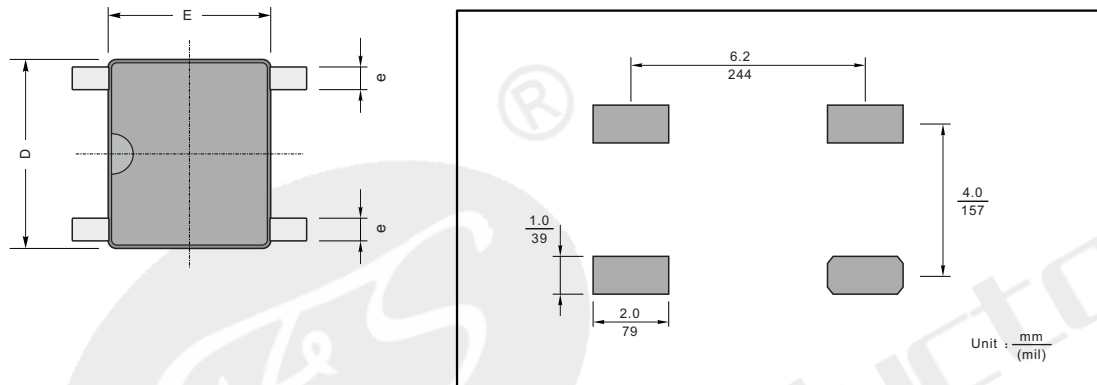


Package Dimension

ABS



The recommended mounting pad size



ABS mechanical data

UNIT		A	C	D	E	H _E	d	e	L	L ₁	a	∠
mm	max	1.5	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.3	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	59	8.7	205	177	252	165	28	37	24	4	
	min	51	5.9	193	166	236	150	20				

Declaration

- FIRST reserves the right to change the specifications, the same specifications of products due to different packaging line mold, the size of the appearance will be slightly different, shipped in kind, without notice! Customers should obtain the latest version information before ordering, and verify whether the relevant information is complete and up-to-date.
- Any semiconductor product under certain conditions has the possibility of failure or failure, The buyer has the responsibility to comply with safety standards and take safety measures when using FIRST products for system design and manufacturing, To avoid To avoid potential failure risks, which may cause personal injury or property damage!
- Product promotion endless, our company will wholeheartedly provide customers with better products!

ATTACHMENT

Revision History

Date	REV	Description	Page
2018.01.01	1.0	Initial release	